Charge Relaxation and Gain Depletion for Candidate Secondary Electron Emission Materials

Z. Insepov<sup>1</sup>, V. Ivanov<sup>2</sup>, J. Elam<sup>1</sup>, B. Adams<sup>1</sup>, and H. Frisch<sup>1,3</sup> <sup>1</sup> Argonne National Laboratory, <sup>2</sup> Muons Inc., <sup>3</sup> University of Chicago



Fig. 1. Resistivity of ZnO/Al2O3 alloy films measured using the four point probe and the mercury probe [1].

 $ZnO/Al_2O_3$  alloy films were prepared using ALD (atomic layer deposition) techniques. By adjusting the ALD pulse sequence, the  $ZnO/Al_2O_3$  alloy film composition was varied from 0-100% ZnO [1]. Fig. 1 shows resistivity of  $ZnO/Al_2O_3$  alloy films that was used in this work.

Materials constants and physical properties of such alloy films, such as surface roughness, resistivity, dielectric constants, film thickness were obtained to be suitable for using these materials as resistive and emissive layers in large-area photodetecting MCP (multichannel plates), as compared to conventional glass substrates.

Charge relaxation and gain depletion mechanisms, effects of a strong electric field, geometry parameters of coating for a large area fast photodetectors were analyzed and discussed [2]. A new ambipolar solid state plasma drift-diffusion

model of the charge relaxation in such materials as  $ZnO/Al_2O_3$  in various combination of the content was proposed that included generation of electrons and holes via impact ionization due to acceleration in a strong electric field [3]. Some of the equations of this model are given below [4-7]:

$$\begin{split} \vec{J}_{e} &= eD_{e}\nabla N_{e} + e\mu_{e}N_{e}\vec{E}, \\ \vec{J}_{h} &= -eD_{h}\nabla N_{h} + e\mu_{h}N_{h}\vec{E}, \\ div \vec{E} &= \frac{\rho}{\varepsilon\varepsilon_{0}}, \rho = N_{h} - N_{e}, \\ \frac{\partial N_{e}}{\partial t} &= \frac{1}{q}\nabla J_{e} = D_{e}\Delta N_{e} + eN_{e}\mu_{e} / \varepsilon\varepsilon_{0}(N_{h} - N_{e}) + G_{ii} \\ \frac{\partial N_{h}}{\partial t} &= -\frac{1}{q}\nabla J_{h} = D_{h}\Delta N_{h} - eN_{h}\mu_{h} / \varepsilon\varepsilon_{0}(N_{h} - N_{e}), \\ \mu_{e,h} &= \sigma_{e,h} / e N_{e,h}, \ D_{e,h} = \mu_{e,h}k_{B}T/e. \end{split}$$

Here *e* is the elemental charge amount (e > 0),  $D_{e,h}$  are the diffusion coefficients, and  $\mu_{e,h}$  are the mobilities of electrons and holes at temperature *T* created by electron impacts and ionization in the space charge field,  $G_{ii}$ . The Einstein relationship between the diffusion coefficients and the mobilities  $D_{e,h}=\mu_{e,h} k_{\rm B} T/e$  allows to use the electricfield-dependent diffusion coefficients;  $N_{e,h}$  are the corresponding carrier densities.  $J_{e,h}$  are the fluxes of carriers.

The following conductivity of AZO film with 20% AI was used:  $\rho = 10^7 (\Omega \text{ cm})$ . The diffusion coefficients of amorphous alumina are unknown. Therefore, we found the diffusion coefficients of alumina via alumina carrier mobilities that are given for some limited mixture content in Ref. [8]. Assuming linear dependence between conductivity and mobility, mobility of a mixture Al<sub>2</sub>O<sub>3</sub>+ZnO was extrapolated from low to high Alcontent.



Fig. 2. The results of our calculation via the drift-diffusion model in spherical geometry, with the diffusion coefficients shown in the plots: a)  $1.2 \times 10^{-11}$ , b)  $1.2 \times 10^{-10}$ , c)  $1.2 \times 10^{-9}$ , and d)  $1.2 \times 10^{-8}$  cm<sup>2</sup>/s.

The calculated results were compared to the results of a simple Maxwell relaxation time model and with the circuit charge relaxation model developed for the MCP device [9]. A pump-probe experiment has been discussed that will be capable of measuring charge relaxation time, and to clearly demonstrate gain depletion [10]. It is based upon the attenuation of pulses traveling along a microwave strip line on an MCP beyond that due to normal resistive losses [11].

References:

[1] J.W. Elam et al, J. of Electrochem. Soc. 150 (6) G339-G347 (2003).

- [2] A.K. Jonscher, Principles of semiconductor device operations, Wiley (1960).
- [3] A.G. Chynoweth, J. Appl. Phys. 31, 1161-1165 (1960).
- [4] A.H. Marshak, Proc. IEEE 72, 148-164 (1984).
- [5] R. Van Overstraeten, Solid St. Electronics 13 (1970) 583-608.
- [6] L.M. Biberman, Proc. IEEE 59, 555-572 (1972).
- [7] Z. Insepov et al, Phys. Rev. A77, 062901 (2008).
- [8] F. Ruske et al, J. Appl. Phys. 107, 013708 (2010).
- [9] A.B. Berkin, V.V. Vasil'yev, Techn. Phys. Lett. 33, 664-666 (2007).
- [10] O.L. Landen et al, Proc. SPIE, Vol. 2002, 2 (1993).
- [11] M. Katayama et al, Rev. Sci. Instrum. 62, 124, (1991).